

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)	Application Number		10551745	
	Filing Date		2007-03-19	
	First Named Inventor	Edmund Riedl		
	Art Unit			
	Examiner Name			
	Attorney Docket Number	I431.131.101/FIN421PCT/US		

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CN	1	20050048758		2005-03-03	Hosseini et al.	
CN	2	20020047217		2002-04-25	Zakel et al.	

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CN	1	2930779	DE		1980-02-07	Tokyo Shibaura Denki K. K.,	<input type="checkbox"/>
CN	2	54150076	JP		1979-11-24	Omron Tateisi Electronics Co.	<input type="checkbox"/>

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CN	3	2000294444	JP		2000-10-20	Sumitomo Electric Industries		<input type="checkbox"/>
CN	4	05237694	JP		1993-09-17	Nippon Steel Corp.		<input type="checkbox"/>
CN	5	2001077049	JP		2001-03-23	Tokyo Shibaura Electric Co.		<input type="checkbox"/>
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CN	1	CHIN et al., Advances in bonding technology for electronic packaging, Journal of Electronic Packaging, Vol. 115, June 1993, 1 pp.	<input type="checkbox"/>

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